

#### **40V N-Channel MOSFET**

## **General Description**

This N-Channel MOSFET has been produced using advanced trench technology to deliver low RDS(on) and optimized BVDSS capability to offer superior performance benefit in the application

## **Features**

- Max r<sub>DS(on)</sub> = 16mΩ at V<sub>GS</sub> = 10V
- Max  $r_{DS(on)} = 21m\Omega$  at  $V_{GS} = 4.5V$
- Fast Switching
- RoHS Compliant

## **Product Summary**

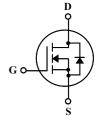
BVDSS	RDSON	ID
40V	16mΩ	50A

## **Applications**

- Inverters
- Power Supplies

# **TO-252 Pin Configuration**





# **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units	
V <sub>DS</sub>	Drain-Source Voltage	40	V	
$V_{GS}$	Gate-Source Voltage	±20	V	
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current 50			
I <sub>DM</sub>	Pulsed Drain Current	150	А	
E <sub>AS</sub>	Drain-Source Avalanche Energy <sup>1</sup>	90	mJ	
P <sub>D</sub> @T <sub>C</sub> =25℃	Total Power Dissipation 45		W	
T <sub>STG</sub>	Storage Temperature Range -55 to 150		$^{\circ}$	
TJ	Operating Junction Temperature Range -55 to 150		$^{\circ}$	

# **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient		40	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-case		2.8	°C/W



### **40V N-Channel MOSFET**

# Electrical Characteristics ( $T_J$ =25 $^{\circ}$ C , unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	40			V
D	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =18A			16	mΩ
R <sub>DS(ON)</sub>		V <sub>GS</sub> =4.5V , I <sub>D</sub> =15A			21	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=250uA$	1		3	V
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =32V, V <sub>GS</sub> =0V			1	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V , V <sub>DS</sub> =0V			±100	nA
gfs	Forward Transconductance <sup>2</sup>	V <sub>DS</sub> =5V , I <sub>D</sub> =10A		15		S
Qg	Total Gate Charge	I <sub>D</sub> =25A		18		
Q <sub>gs</sub>	Gate-Source Charge	V <sub>DS</sub> =20V		3		nC
Q <sub>gd</sub>	Gate-Drain Charge	V <sub>GS</sub> = 10V		5		
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DS</sub> =20V		8		
T <sub>r</sub>	Rise Time	I <sub>D</sub> =25A		15		
T <sub>d(off)</sub>	Turn-Off Delay Time	R <sub>GEN</sub> =6Ω		32		ns
T <sub>f</sub>	Fall Time	V <sub>GS</sub> =10V		7		
C <sub>iss</sub>	Input Capacitance			1400		
Coss	Output Capacitance	V <sub>DS</sub> =20V , V <sub>GS</sub> =0V , f=1MHz		200		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			90		

## **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
trr	Reverse Recovery Time	I <sub>E</sub> =25A		15		ns
Qrr	Reverse Recovery Charge	di/dt=100A/µs		30		nC
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =20A			1.2	V

## Notes:

1.Starting T<sub>J</sub> = 25  $^{\circ}$ C, L = 0.5mH, I<sub>D</sub> =19 A, V <sub>DD</sub> = 40 V, V<sub>GS</sub> = 10 V.

2.Pulse Test: Pulse Width < 300µs, Duty cycle < 2.0%.

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